



## **CPC1008N** Single-Pole, Normally Open 4-Pin SOP OptoMOS® Relay

Parameter	Rating	Units
Blocking Voltage	100	V <sub>P</sub>
Load Current	150	mA <sub>rms</sub> / mA <sub>DC</sub>
On-Resistance (max)	8	Ω

#### **Features**

- 1500V<sub>rms</sub> Input/Output Isolation
  Small 4-Pin SOP Package
- Low Drive Power Requirements
- High Reliability
- · Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Wave Solderable
- Tape & Reel Version Available

## **Applications**

- Instrumentation
  - Multiplexers
  - Data Acquisition
  - Electronic Switching
  - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security Systems
- Aerospace
- Industrial Controls
- Reed Relay Replacement

## **Description**

CPC1008N is a miniature, low-voltage, low on-resistance, single-pole, normally open (1-Form-A) solid state relay in a 4-Pin SOP package. It uses IXYS Integrated Circuits Division's patented, optically coupled, OptoMOS architecture to provide 1500Vrms of input/output isolation.

Using IXYS Integrated Circuits Division's state of the art double-molded vertical construction packaging, the CPC1008N is one of the world's smallest relays. It is ideal for replacing larger, less-reliable reed and electromechanical relays.

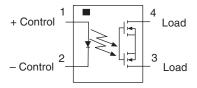
## **Approvals**

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- EN/IEC 60950-1 Certified Component: Certificate B 13 12 82667 003

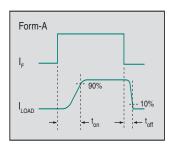
## **Ordering Information**

Part #	Description
CPC1008N	4-Pin SOP (100/tube)
CPC1008NTR	4-Pin SOP (2000/reel)

## **Pin Configuration**



# **Switching Characteristics** of Normally Open Devices











## Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	100	$V_{P}$
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	Α
Input Power Dissipation	70	mW
Total Power Dissipation <sup>1</sup>	400	mW
Isolation Voltage, Input to Output (60 Seconds)	1500	V <sub>rms</sub>
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

## Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics					'	
Load Current						
Continuous <sup>1</sup>	-	$I_{L}$			150	$mA_{rms} / mA_{DC}$
Peak	t=10ms	I <sub>LPK</sub>	-	-	±350	mA <sub>P</sub>
On-Resistance <sup>2</sup>	I <sub>L</sub> =150mA	R <sub>ON</sub>	-	4.8	8	Ω
Off-State Leakage Current	$V_L = 100 V_P$	I <sub>LEAK</sub>	-	-	1	μΑ
Switching Speeds						
Turn-On	I -5m \ \/ -10\/	t <sub>on</sub>	-	1	2	ma
Turn-Off	I <sub>F</sub> =5mA, V <sub>L</sub> =10V	t <sub>off</sub>	-	0.17	1	ms
Output Capacitance	I <sub>F</sub> =0mA, V <sub>L</sub> =50V, f=1MHz	C <sub>OUT</sub>	-	6	-	pF
Input Characteristics				•	1	
Input Control Current to Activate 3	I <sub>L</sub> =150mA	l <sub>F</sub>	-	0.45	2	mA
Input Control Current to Deactivate	-	I <sub>F</sub>	0.2	-	-	mA
Input Voltage Drop	I <sub>F</sub> =5mA	$V_{F}$	0.9	1.2	1.4	V
Reverse Input Current	V <sub>R</sub> =5V	I <sub>R</sub>	-	-	10	μΑ
Common Characteristics		•		1	1	•
Capacitance, Input to Output	-	$C_{I/O}$	-	1	-	pF

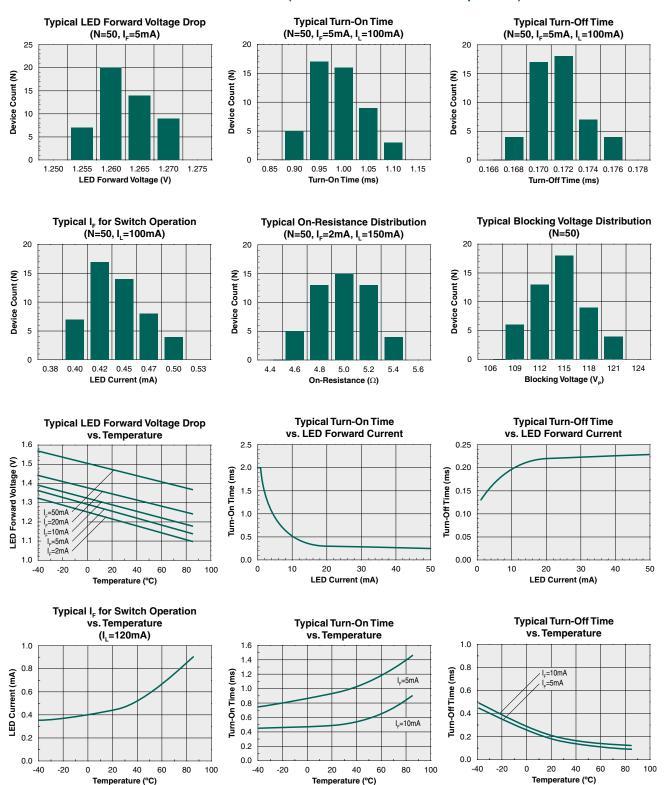
Load current derates linearly from 150mA @ 25°C to 120mA @ 85°C. Measurement taken within 1 second of on time.

<sup>1</sup> Derate linearly 3.33 mW / °C

For high temperature operation (>60°C) a minimum LED drive current of 4mA is recommended.



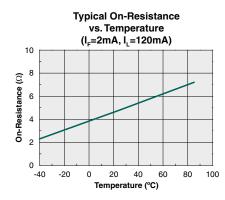
## PERFORMANCE DATA (@ 25°C Unless Otherwise Specified)\*

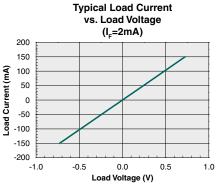


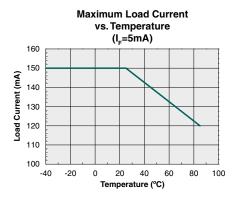
<sup>\*</sup>The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

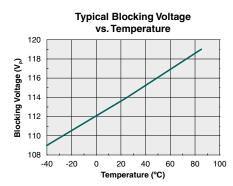


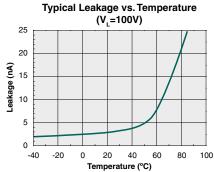
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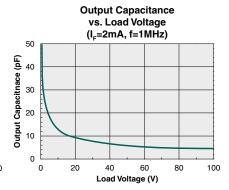


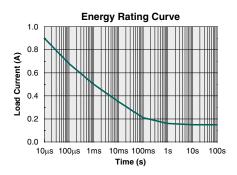












<sup>\*</sup>The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.



## **Manufacturing Information**

## **Moisture Sensitivity**

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1008N	MSL 3

## **ESD Sensitivity**



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

## **Reflow Profile**

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time	
CPC1008N	260°C for 30 seconds	

## **Board Wash**

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.



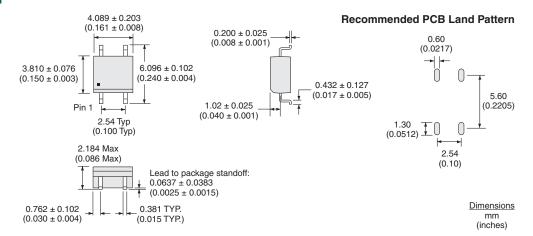




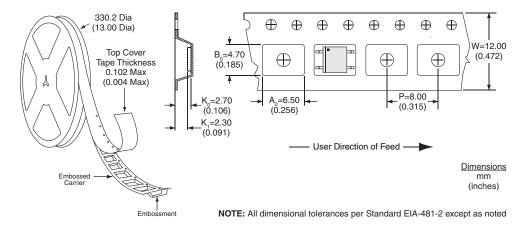


#### **MECHANICAL DIMENSIONS**

#### **CPC1008N**



## **CPC1008NTR Tape & Reel**



## For additional information please visit our website at: www.ixysic.com

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